

METHOD AND APPARATUS FOR PROVIDING AN INTEGRATED PRINTED
CIRCUIT BOARD REGISTRATION COUPON

Abstract of the Disclosure

5 A device includes a plane metallization layer, and a plane plated through
hole attached to the plane metallization layer and terminating at the at a major
exterior surface with a plurality of component mounting pads. The plated through
hole is attached to the plane metallization layer. The plane plated through hole is
electrically isolated from the plurality of component mounting pads at the exterior
10 surface. A method for testing the device includes contacting the signal carrying
through hole, and contacting the plane through hole, and checking for current flow
between the signal carrying through hole and the plane through hole. If current
flows between the signal carrying through hole and the plane through hole the
device fails. If no current flows between the signal carrying through hole and the
15 plane through hole the device passes.

"Express Mail" mailing label number: EV 332568799 US

Date of Deposit: September 23, 2003

This paper or fee is being deposited on the date indicated above with
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